2309409-2 V ACTIVE

DDR4 DIMM

TE Internal #: 2309409-2

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 260 Position, .02 in [.5 mm]

Centerline, DDR4 DIMM

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: Small Outline (SO) Stack Height: **5.2 mm [.205 in]** Module Orientation: Right Angle

Number of Positions: 260

Centerline (Pitch): .5 mm [.02 in]

All DDR4 SO DIMM Sockets (39)

Features

Cable-to-Board
Printed Circuit Board
Small Outline (SO)
1
2
Right Angle
260
1.2 V
1.2 V
Both Ends

High Temperature Thermoplastic

Latch Material



Retention Post Location	Both Ends
Module Key Type	Offset Left
Ejector Type	Locking
Connector Profile	Low
Contact Features	
Memory Socket Type	Memory Card
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.5 A
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.127 μm[5 μin]
Termination Features	
Insertion Style	Cam-In
Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
Mating Alignment Type	Standard Keying
PCB Mount Retention	With
PCB Mount Retention Type	Solder Peg
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.5 mm[.02 in]
Dimensions	
Stack Height	5.2 mm[.205 in]
Row-to-Row Spacing	8.2 mm[.322 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
Operation/Application	
Circuit Application	Power
Industry Standards	
UL Flammability Rating	UL 94V-0



Packaging Features

Packaging Quantity	800
Packaging Method	Tape & Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | DDR4 DIMM





DIMM Sockets(69)

SO DIMM Sockets(39)

Customers Also Bought

















Documents

Product Drawings

DDR4 SODIMM 260P 5.2H STD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2309409-2_1.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2309409-2_1.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2309409-2_1.3d_stp.zip

SO DIMM Sockets, Small Outline (SO), Stack Height .205 in [5.2 mm], Right Angle Module Orientation, 260 Position, .02 in [.5 mm] Centerline, DDR4 DIMM



English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English